

## N-Channel Enhancement Mode Power MOSFET

### Description

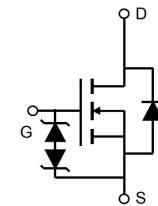
The GT011N03D5E uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge. It can be used in a wide variety of applications.

### General Features

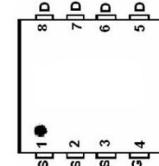
- $V_{DS}$  30V
- $I_D$  (at  $V_{GS} = 10V$ ) 209A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) < 0.95mΩ
- $R_{DS(ON)}$  (at  $V_{GS} = 4.5V$ ) < 1.8mΩ
- 100% Avalanche Tested
- RoHS Compliant
- ESD (HBM) : 4KV

### Application

- Power switch
- DC/DC converters



Schematic diagram



pin assignment



DFN5X6-8L

### Ordering Information

Device	Package	Marking	Packaging
GT011N03D5E	DFN5X6-8L	GT011N03	5000pcs/Reel

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Continuous Drain Current	$I_D$	209	A
Pulsed Drain Current (note1)	$I_{DM}$	836	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	89	W
Single pulse avalanche energy (note2)	$E_{AS}$	361	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 175	°C

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	55	°C/W
Maximum Junction-to-Case	$R_{thJC}$	1.4	°C/W

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 50$	$\text{uA}$
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.7	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	--	0.86	0.95	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$	--	1.43	1.8	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{GS}} = 5\text{V}, I_D = 10\text{A}$	--	37	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1.0\text{MHz}$	--	5950	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	2130	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	570	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 15\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	--	98	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	16	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	11	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 30\text{A}, R_G = 1.6\Omega$	--	13	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	7.5	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	51	--	
Turn-off Fall Time	$t_f$		--	8.6	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	209	A
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 30\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F = 30\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A/us}$	--	112	--	$\text{nC}$
Reverse Recovery Time	$T_{\text{rr}}$		--	32	--	ns

**Notes**

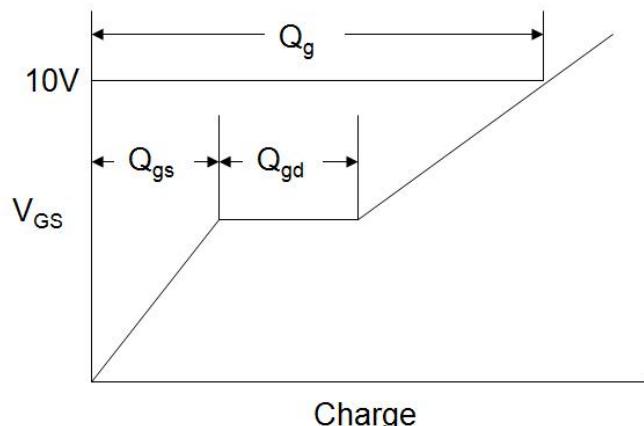
1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$

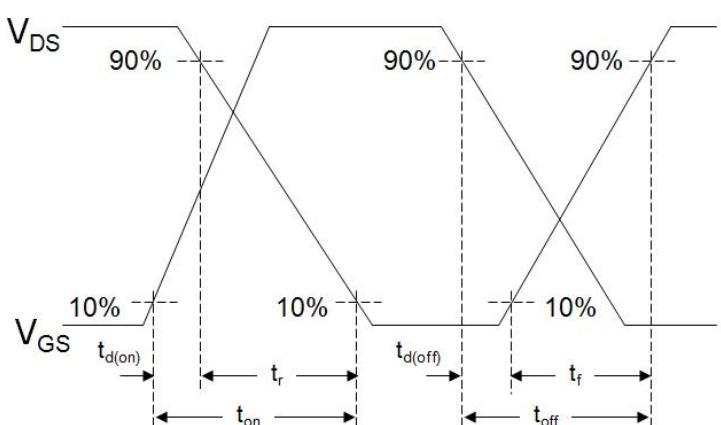
The table shows the minimum avalanche energy, which is 992mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

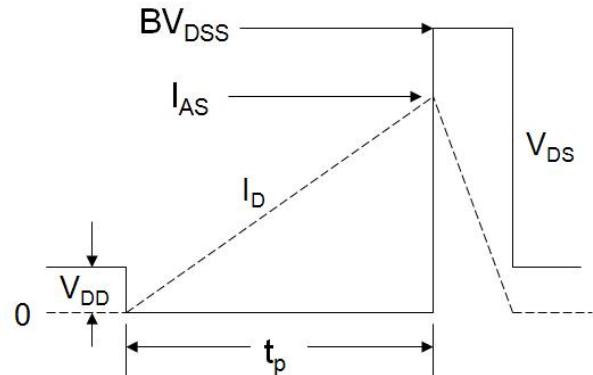
### Gate Charge Test Circuit



### Switch Time Test Circuit

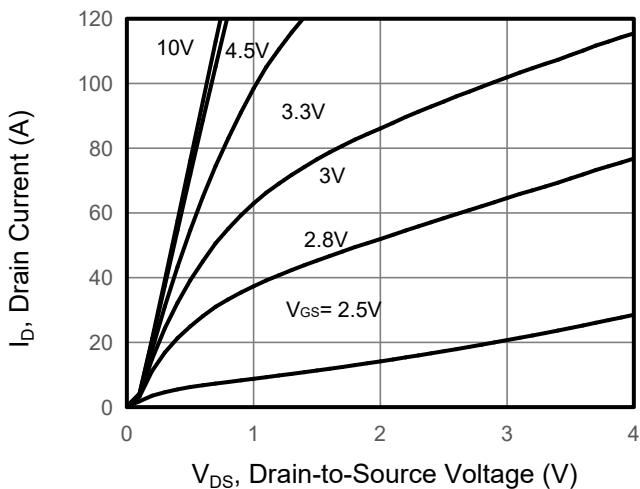


### EAS Test Circuit

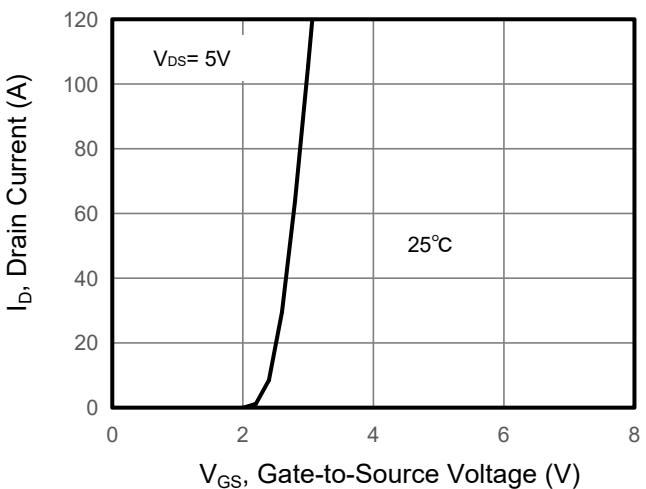


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

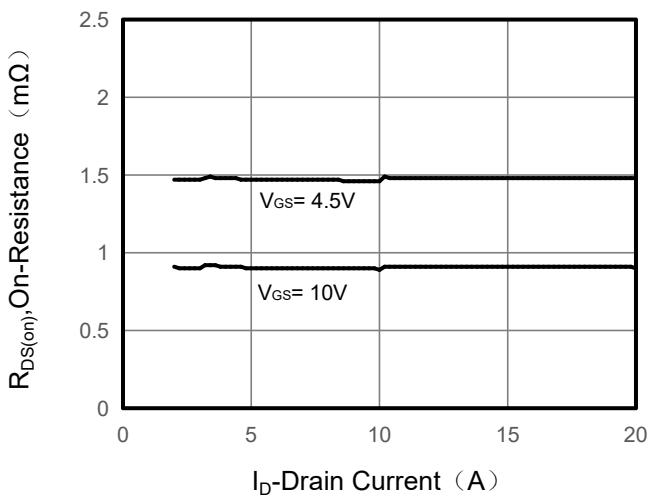
**Figure 1. Output Characteristics**



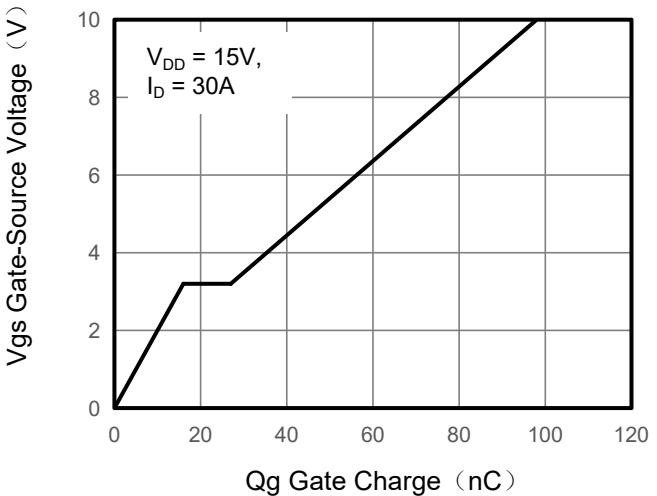
**Figure 2. Transfer Characteristics**



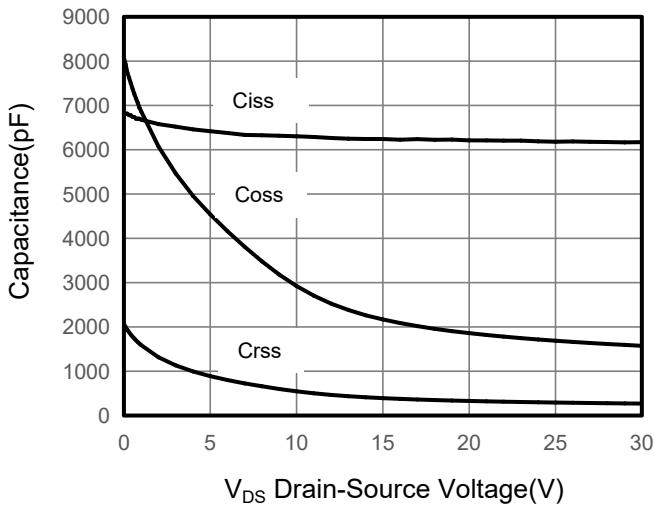
**Figure 3. Drain Source On Resistance**



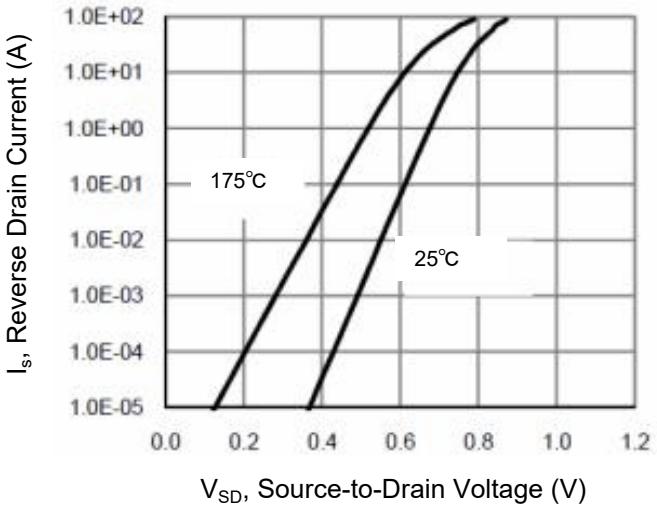
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

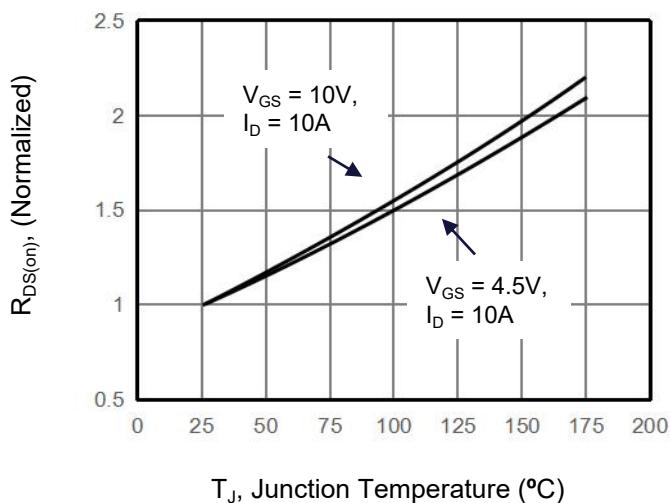


**Figure 6. Source-Drain Diode Forward**

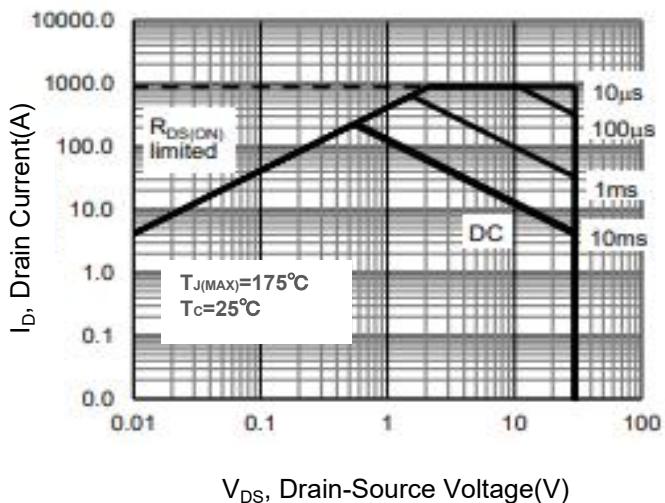


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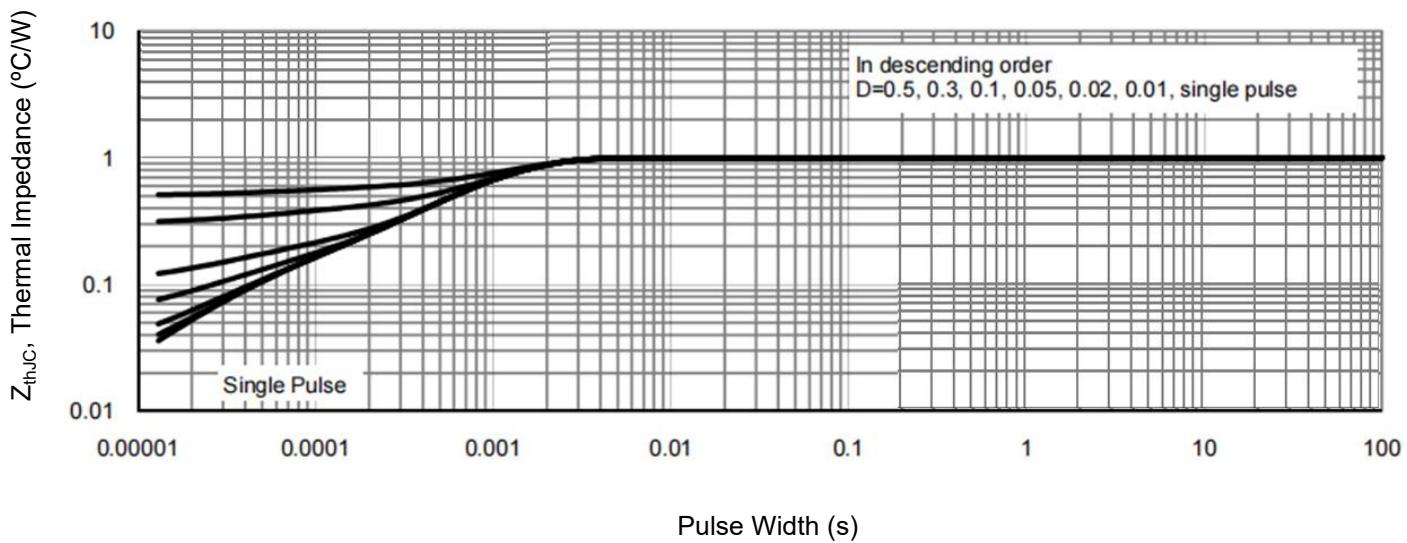
**Figure 7. Drain-Source On-Resistance**



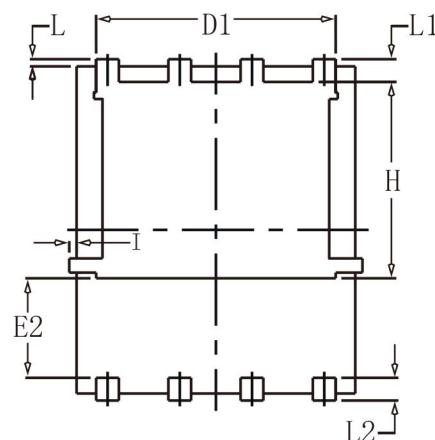
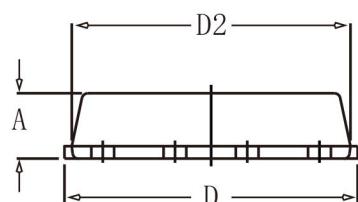
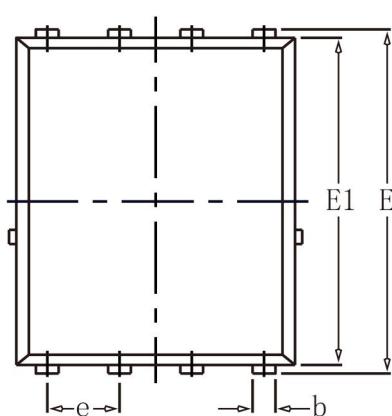
**Figure 8. Safe Operation Area**



**Figure 9. Normalized Maximum Transient Thermal Impedance**



## DFN5X6-8L Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN	MAX	MIN	MAX
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.59	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	-	0.0630	-
e	1.27	BSC	0.05	BSC
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	-	0.18	-	0.0070